

L Number	Hits	Search Text	DB	Time stamp
2	32	((mcm or (multi adj chip adj module)) and ((insulation or dielectric) with substrate)) and (mold\$ with conduct\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 12:58
3	32	((mcm or (multi adj chip adj module)) and ((insulation or dielectric) with substrate)) and (mold\$ with (conduct\$ or electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 13:17
4	0	("0578411").PN.	EPO	2002/03/23 13:17
5	0	"0578411"	EPO	2002/03/23 13:18
6	2	"0578411"	EPO; DERWENT	2002/03/23 13:18
7	32	auyeung	EPO	2002/03/23 13:19
8	3	auyeung and heat	EPO	2002/03/23 13:19
1	830	(mcm or (multi adj chip adj module)) and ((insulation or dielectric) with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 13:44
9	195	(heat adj sink) near electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 13:45
10	37	((heat adj sink) near electrode) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 13:53
11	0	("9293987").PN.	JPO	2002/03/23 13:53
12	0	"9293987"	USPAT	2002/03/23 13:53
13	0	"9293987"	USPAT; JPO	2002/03/23 13:53
14	0	"49293987"	USPAT; JPO	2002/03/23 13:59
15	0	jp409293987.pn.	USPAT; JPO	2002/03/23 13:59
16	0	jp49293987.pn.	USPAT; JPO	2002/03/23 13:59
17	0	jp9293987.pn.	USPAT; JPO	2002/03/23 13:59
18	0	9293987.pn.	USPAT; JPO	2002/03/23 13:59
19	0	"9293987"	USPAT; JPO	2002/03/23 14:01
20	24	((mcm or (multi adj chip adj module)) and ((insulation or dielectric) with substrate)) and (liquid near (conduct\$ or metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 14:07
21	283	257/\$.cccls. and (liquid near (conduct\$ or metal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 14:51
22	1	("4323914").PN.	USPAT	2002/03/23 14:14
23	1		USPAT	2002/03/23 14:15
24	69	4323914.URPN.	USPAT	2002/03/23 14:18
25	10	257/\$.cccls. and (mold\$ adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 15:00
26	427	((mcm or (multi adj chip adj module)) and ((insulation or dielectric) with substrate)) and (heat and sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 15:07
27	14	((mcm or (multi adj chip adj module)) and ((insulation or dielectric) with substrate)) and ((cooper or Ag or silver or cu) near epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 15:43
28	11	5866952.URPN.	USPAT	2002/03/23 15:27

29	225	257/\$.ccls. and ((cooper or Ag or silver or cu) near epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 15:44
30	735	257/\$.ccls. and ((copper or Ag or silver or cu) near (epoxy or fille\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 15:54
31	288	(257/\$.ccls. and ((copper or Ag or silver or cu) near (epoxy or fille\$))) and mold\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 15:49
32	6	257/\$.ccls. and (mold\$ with ((copper or Ag or silver or cu) near (epoxy or fille\$)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:04
33	1	("5700723").PN.	USPAT	2002/03/23 16:22
34	0	6201301.URPN.	USPAT	2002/03/23 16:17
35	0	6201301.URPN.	USPAT	2002/03/23 16:17
36	26	("5074947" "5172301" "5175612" "5311060" "5386144" "5399898" "5409863" "5410805" "5410806" "5463529" "5466635" "5500555" "5514327" "5527743" "5537342" "5552634" "5568683" "5570272" "5572069" "5621616" "5635244" "5637920" "5663872" "5700723" "5869886" "6002163").PN.	USPAT	2002/03/23 16:17
37	2	chip and dfpr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:24
38	1	die with free with package with resist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:25
39	30938	insulat\$ with (fin o r(heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:27
40	6106	insulat\$ with (fin or (heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:31
41	1098	(insulat\$ with (fin or (heat adj sink))) and (mcm or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:29
42	196	((insulat\$ with (fin or (heat adj sink))) and (mcm or chip)) and (mold or encapsulant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:29
43	695	insulat\$ near (fin or (heat adj sink))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:33

44	130	(insulat\$ near (fin or (heat adj sink))) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:32
45	137	(insulat\$ with fin) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:43
46	9	257/703.ccls. and fin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:44
47	14	257/732.ccls. and mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:48
48	1398	dam with mold\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:50
49	475	(dam with mold\$) and (chip or package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:52
50	36	257/723.ccls. and dam	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 16:55
51	77	mold near dam	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 17:07
52	172	(mole or cap) adj telescope\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 17:09
54	1	((mold or cap) adj telescope\$) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 17:09
53	187	(mold or cap) adj telescope\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 17:14
55	53	257?\$.ccls. and telescope\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 17:20
56	100	chips with dam	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/23 17:45
57	0	2001196521.URPN.	USPAT	2002/03/23 17:38
58	0	2001196521.URPN.	USPAT	2002/03/23 17:38
59	11	5160296.URPN.	USPAT	2002/03/23 17:38
60	0	20020025601.URPN.	USPAT	2002/03/23 17:39
61	0	20020025601.URPN.	USPAT	2002/03/23 17:40

62	8	("5729437" "5776798" "5973263" "5989982" "5990545" "6087202" "6093584" "6228676").PN.	USPAT	2002/03/23 17:40
63	178	chips and (mold\$ with dam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2002/03/23 18:50
64	26	("4218701" "4502903" "4621035" "4814943" "4903169" "5018005" "5136365" "5295044" "5321240" "5327010" "5336931" "5350645" "5362652" "5386342" "5389738" "5416358" "5422514" "5477047" "5528222" "5536466" "5558679" "5601941" "5605547" "5612513" "5646828" "5866441").PN.		2002/03/23 17:49